

**N-Ch 100V Fast Switching MOSFETs**
**Description**

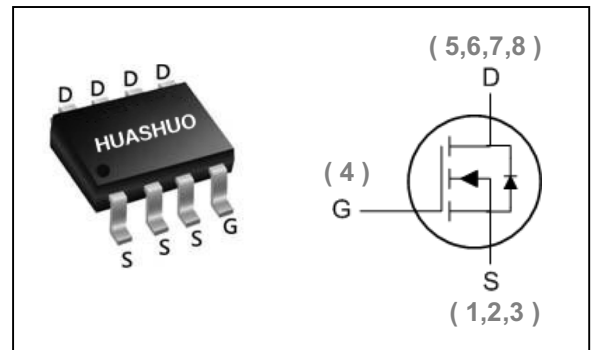
The HSM0016 is the high cell density trenched N-ch MOSFETs, which provide excellent R<sub>DS(ON)</sub> and gate charge for most of the synchronous buck converter applications.

The HSM0016 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- Green Device Available
- Super Low Gate Charge
- Excellent C<sub>dv/dt</sub> effect decline
- Advanced high cell density Trench technology

**Product Summary**

V <sub>DS</sub>	100	V
R <sub>DS(ON),max</sub>	47	mΩ
I <sub>D</sub>	3.6	A

**SOP8 Pin Configuration**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	3.6	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	2.9	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	15	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	36.5	mJ
I <sub>AS</sub>	Avalanche Current	27	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	1.5	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup>	---	85	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	24	°C/W



**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	100	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BVDSS Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	0.098	---	V/°C
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =3A	---	---	47	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =2A	---	---	50	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.0	---	2.5	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-5.52	---	mV/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	10	uA
		V <sub>DS</sub> =80V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	100	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =3A	---	6.2	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	1.6	---	Ω
Q <sub>g</sub>	Total Gate Charge (10V)	V <sub>DS</sub> =80V, V <sub>GS</sub> =10V, I <sub>D</sub> =3A	---	60	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	9.2	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	9.9	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =50V, V <sub>GS</sub> =10V, R <sub>G</sub> =3.3Ω I <sub>D</sub> =3A	---	10.8	---	ns
T <sub>r</sub>	Rise Time		---	27	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	56	---	
T <sub>f</sub>	Fall Time		---	24	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz	---	3848	---	pF
C <sub>oss</sub>	Output Capacitance		---	137	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	82	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	3.6	A
I <sub>SM</sub>	Pulsed Source Current <sup>2,5</sup>		---	---	15	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	IF=3A, dI/dt=100A/μs, T <sub>J</sub> =25°C	---	25	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge		---	29	---	nC

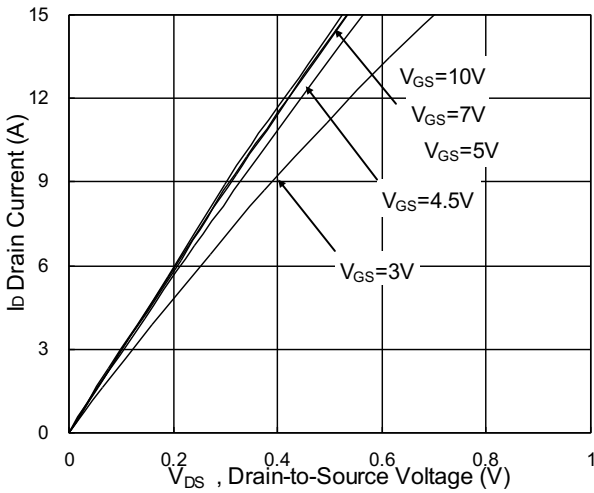
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=25V,V<sub>GS</sub>=10V,L=0.1mH,I<sub>AS</sub>=27A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

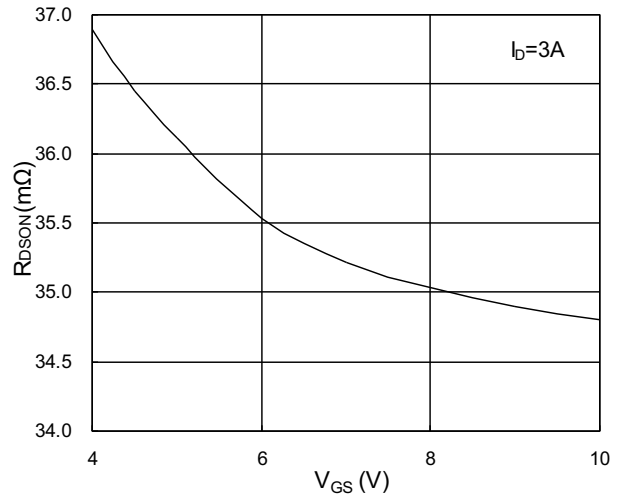


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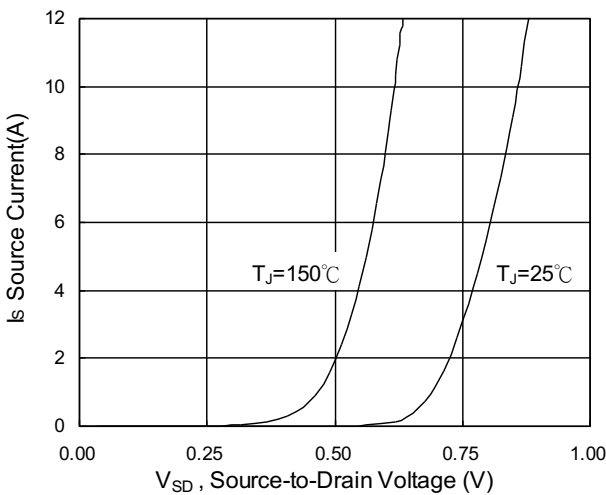
**Typical Characteristics**



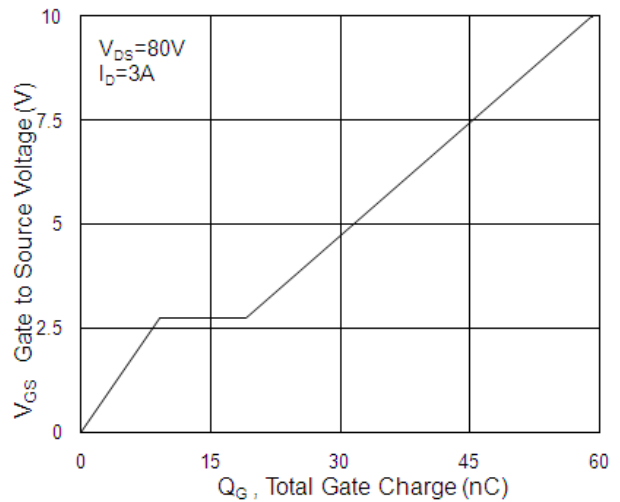
**Fig.1 Typical Output Characteristics**



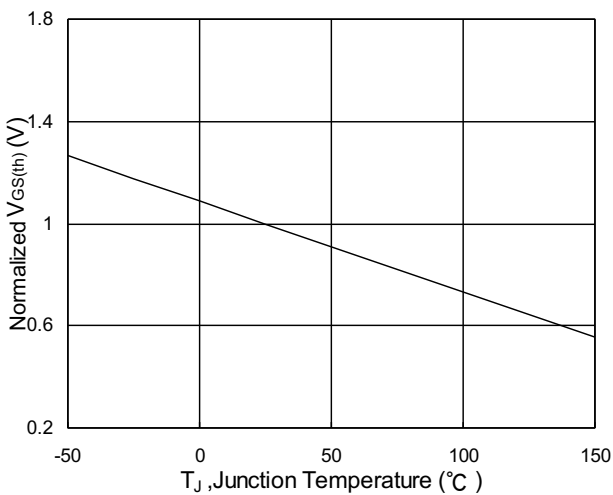
**Fig.2 On-Resistance vs. G-S Voltage**



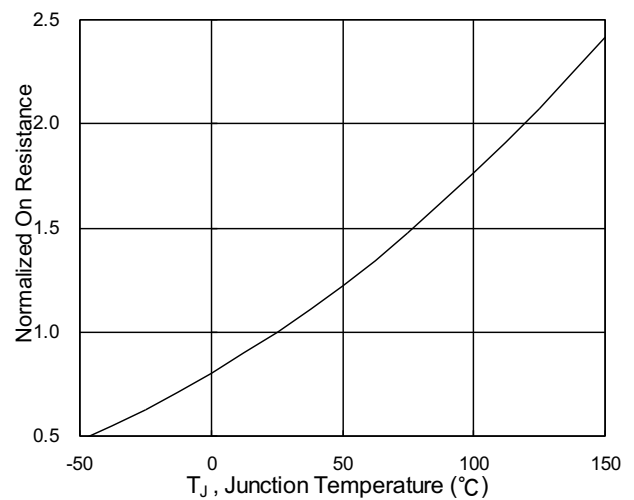
**Fig.3 Forward Characteristics of Reverse**



**Fig.4 Gate-Charge Characteristics**



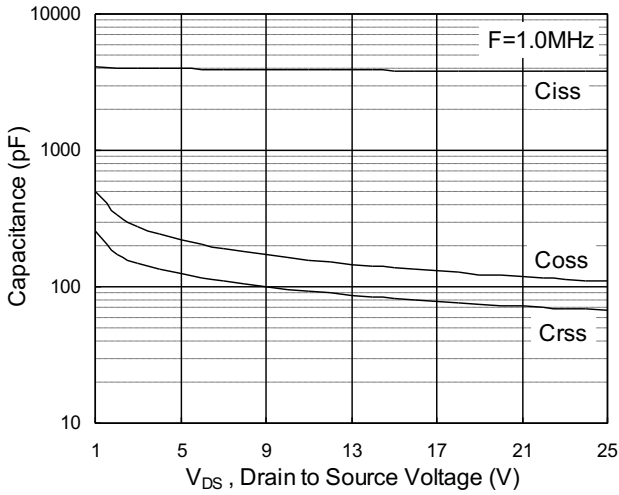
**Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>**



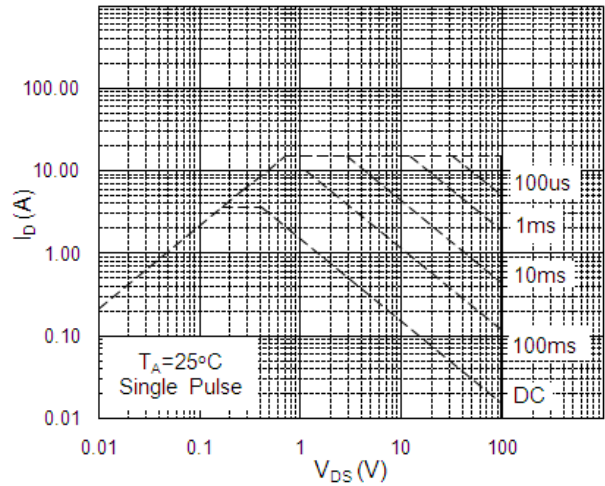
**Fig.6 Normalized R<sub>DS(on)</sub> vs. T<sub>J</sub>**



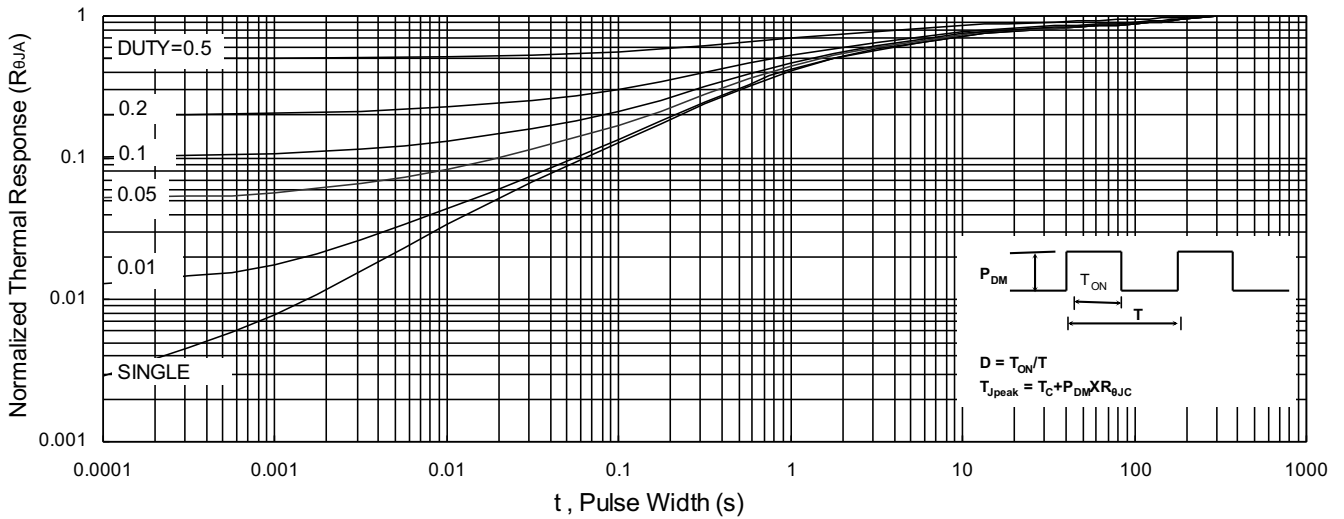
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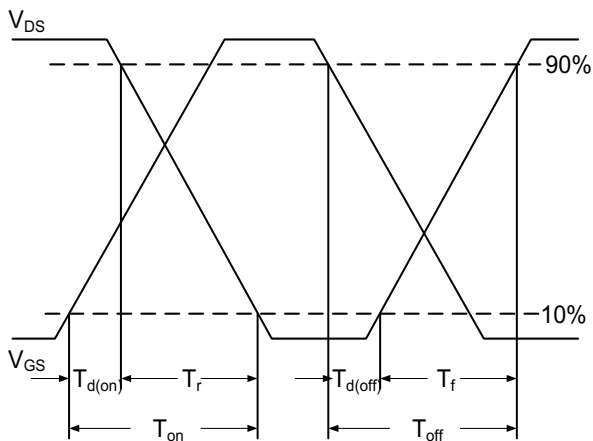
**Fig.7 Capacitance**



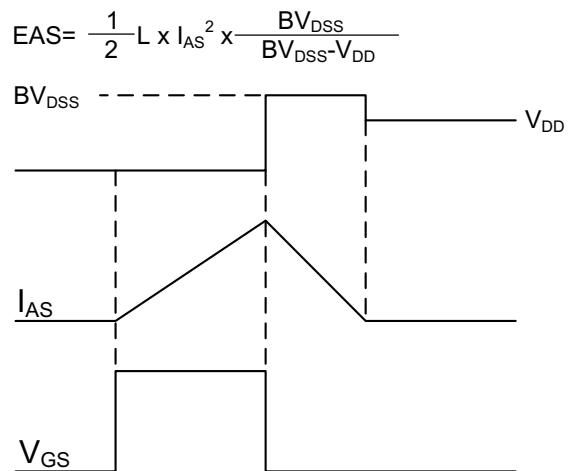
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching**



## Ordering Information

Part Number	Package code	Packaging
HSM0016	SOP-8	2500/Tape&Reel

